



Material Content Data Sheet



Sales Product Name	TLE9835QX			Issued		28. August 2013		
MA#	MA000985222							
Package	PG-VQFN-48-29			Weight*		130.22 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.983	3.83	3.83	38268	38268
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		550	
	non noble metal	iron	7439-89-6	1.433	1.10		11006	
	non noble metal	copper	7440-50-8	58.193	44.68	45.85	446885	458579
wire	noble metal	gold	7440-57-5	0.782	0.60	0.60	6009	6009
encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1389	
	plastics	epoxy resin	-	7.656	5.88		58792	
	inorganic material	silicondioxide	60676-86-0	52.446	40.28	46.30	402751	462932
leadfinish	non noble metal	tin	7440-31-5	2.596	1.99	1.99	19939	19939
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4714	4714
glue	plastics	epoxy resin	-	0.286	0.22		2199	
	noble metal	silver	7440-22-4	0.958	0.74	0.96	7360	9559
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com